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Part Number: [0736441216](#)
Status: **Active**
Overview: [hdm](#)
Description: 2.00mm (.079") Pitch HDM® Board-to-Board Backplane Header, Vertical, SMC, Press-Fit, Guide Post Location B, Polarizing Key Position N/A, 144 Circuits

Documents:

3D Model	Drawing (PDF)
Test Summary (PDF)	RoHS Certificate of Compliance (PDF)

Agency Certification

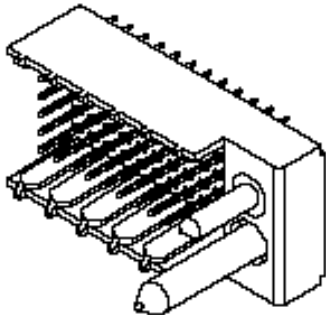
CSA	LR19980
UL	E29179

General

Product Family	Backplane Connectors
Series	73644
Application	Backplane
Comments	Standard Press-Fit
Component Type	PCB Header
Overview	hdm
Product Name	HDM®
Style	N/A

Physical

Circuits (Loaded)	144
Circuits (maximum)	144
Color - Resin	Black, Natural
Durability (mating cycles max)	250
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	Yes
Keying to Mating Part	None
Material - Metal	Phosphor Bronze, Stainless Steel
Material - Plating Mating	Gold
Material - Plating Termination	Gold
Material - Resin	High Temperature Thermoplastic
Number of Columns	24
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length (in)	0.138 In
PC Tail Length (mm)	3.50 mm
PCB Locator	No
PCB Retention	Yes
PCB Thickness Recommended (in)	0.098 In
PCB Thickness Recommended (mm)	2.50 mm
Packaging Type	Tube
Pitch - Mating Interface (in)	0.079 In
Pitch - Mating Interface (mm)	2.00 mm
Pitch - Term. Interface (in)	0.079 In
Pitch - Term. Interface (mm)	2.00 mm
Plating min: Mating (µin)	30
Plating min: Mating (µm)	0.75
Plating min: Termination (µin)	2
Plating min: Termination (µm)	0.05



Series

image - Reference only

EU RoHS

**ELV and RoHS
Compliant**
REACH SVHC
Contains SVHC: No
Halogen-Free
Status

China RoHS



Not Reviewed

**Need more information on product
environmental compliance?**

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of
Compliance, [click here](#)

Please visit the [Contact Us](#) section for any
non-product compliance questions.

Search Parts in this Series

[73644Series](#)

Mates With

[73632](#) HDM PLUS® Board-to-Board
Daughtercard Receptacle. [73780](#) HDM®
Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ

*Tooling specifications and manuals are
found by selecting the products below.
Crimp Height Specifications are then
contained in the Application Tooling
Specification document.*

Global

Description	Product #
Flat Rock Tooling for	0622013700
Pneumatic Press	
HDM® Backplane	0621001400
Insertion Signal	
Contact Tool	
HDM® Backplane	0622005703
Insertion Head for	
144 Positions	

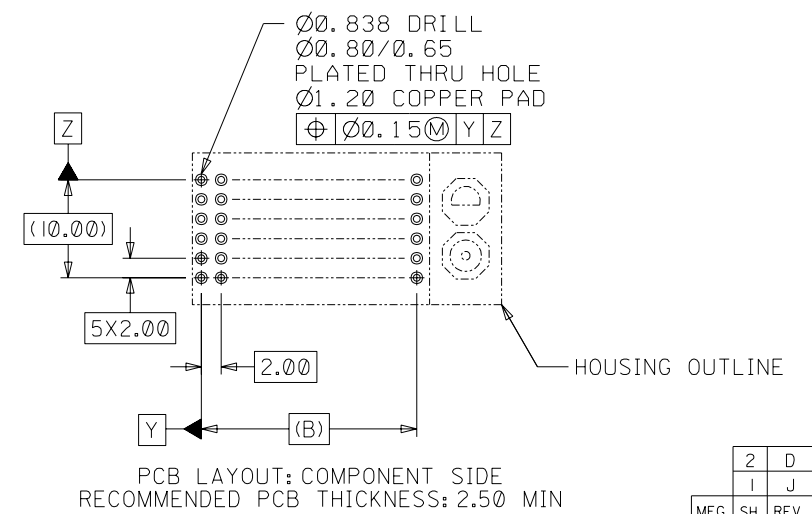
Polarized to PCB	No	Extraction Tool	0621001000
Stackable	No		
Surface Mount Compatible (SMC)	Yes		
Temperature Range - Operating	-55°C to +105°C		
Termination Interface: Style	Through Hole - Compliant Pin		
Electrical			
Current - Maximum per Contact	1A		
Data Rate	1.0 Gbps		
Real Signals (per 25mm)	75		
Shielded	No		
Voltage - Maximum	250V AC		
Material Info			
Reference - Drawing Numbers			
Packaging Specification	PK-70873-0818		
Sales Drawing	SDA-73644-****		

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73644	4	3	2	73644
1. MATERIALS: HOUSING - LIQUID CRYSTAL POLYMER (LCP), GLASS-FILLED, UL94V-0, COLOR: BLACK, TERMINAL - PHOSPHOR BRONZE. 2. FINISHES: SELECTIVE GOLD (Au) IN CONTACT AREA, 0.00076mm MINIMUM THICKNESS; NICKEL (Ni) AND GOLD FLASH OVERALL SELECTIVE GOLD (Au) IN CONTACT AREA, 0.00076mm MIN. THICKNESS; SELECTIVE TIN/LEAD (Sb/Pb) IN TAIL AREA; NICKEL (Ni) OVERALL.				



				I	REVISED ECR UDT2000-0348 BINGHAM 99/10/12	DIMENSIONS SHOWN (METRIC) INCH UNLESS OTHERWISE SPECIFIED TOLERANCES: ANGULAR $\pm 1/2^\circ$		$\nabla = 0$ $\blacktriangledown = 0$		REVISE ONLY ON CAD SYSTEM	
				H	REVISED ECR UDT1999-0662 BINGHAM 99/05/18	INCH METRIC 3 PLACE $\pm$ N/A --- 2 PLACE $\pm$ N/A ± 0.05 1 PLACE --- ± 0.10		TITLE SALES ASSY, HDM BACKPLANE MODULE, POLAR/GUIDE OPTION			
J REVISED ECR UCP2003-2260 THOMAS 03/04/25				G	REVISED ECR UDT1999-0476 BINGHAM 98/12/21	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		 MOLEX INCORPORATED LISLE, ILL. 60532 U.S.A.		SHEET NO. 1 OF 2	DATE 96/12/18
LTR. REVISIONS				LTR. REVISIONS	DRWG. BY JRR CHK'D. BY SMR APP'D. BY CAB SCALE 2 : 1		PART NO. SEE CHART DRWG. NO. SDA-73644-*****		FILE NAME S73644X1.DGN	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.	DIV. DA SIZE B

Данный компонент на территории Российской Федерации

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<http://moschip.ru/get-element>

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Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

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